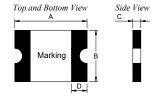
1, Physical Dimensions(size of 1206)

Unit:mm

Part Number	A		В		С		D	Marking	
	Min	Max	Min	Max	Min	Max	Min	Marking	
NSMD150/16	3.00	3.40	1.40	1.80	0.80	1.30	0.25	T15	



2. Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I max (A)	Ttrip (Max time Current(A)		Pd _{typ} (W)	$R_{min} (\Omega)$	$R1_{max}$ (Ω)
NSMD150/16	1.50	3.00	16	100	8.00	0.30	0.60	0.030	0.210

 I_{H} : Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

 $I_{\,\text{max}}\!\!:$ Maximum fault current device can withstand without damage at rated voltage.

T trip: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R min: Minimum resistance of device prior to trip at 25°C.

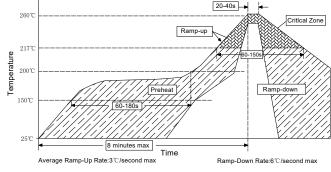
R1 max: Maximum resistance of device is measured one hours post reflow at 25°C.

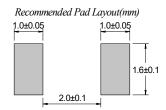
Noted: All electrical function test is conducted after PCB mounted.

3. Thermal Derating

NSMD150/16	Maximum ambient operating temperature									
NSWID130/10	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C	
Hold Current(A)	2.20	1.99	1.77	1.50	1.34	1.23	1.10	1.01	0.84	
Trip Current(A)	4.40	3.98	3.54	3.00	2.68	2.46	2.20	2.02	1.68	

4. Solder Reflow Recommendations





Notes:If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5. Package Information

Packing quantity:3000CS/Reel

Note:Reel packaging per EIA-481-1 standard

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